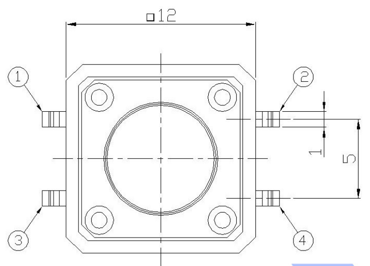
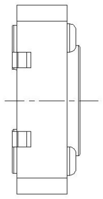
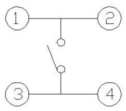


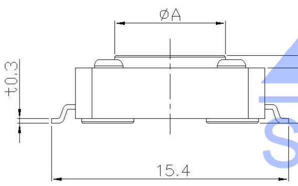


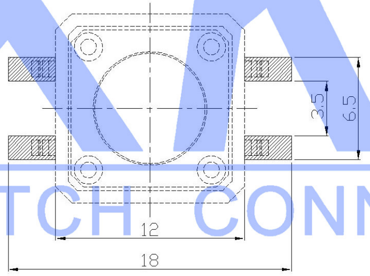
CIRCUIT DIAGRAM



Code-X	H	Code-X	
A	4.3	O	
B	4.5	P	
C	5.0	Q	
D	5.5	R	
E	6.0	S	
F	6.5	T	
G	7.0	U	
H	7.5	V	
I	8.0	W	
J	8.5	X	
K	9.0	Y	
L	9.5	Z	
M	10.0	19	
N	10.5		

P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are recommended for reflow soldering





SPECIFICATION

Contact Rating	50mA 12V DC
Contact Resistance	100mΩ max.
Insulation Resistance	100MΩ min. 500V DC
Dielectric Strength	250V AC/1 minute
Travel	0.25mm
Operating Temp.	-25 C +70 C
Storage Temp.	-30 C +80 C

PAPT NO	TS-1103S-X-X
Operating Force	B:160gf C:260gf
Height	Code-X

⑤	Terminal	——	2	Brass（0.30t）	ag
④	Contact	——	1	F.ag/SUS	
③	Base	——	1	PA46	
②	Cover	——	1	Brass	Ti
①	Keystake	——	1	PA46	
ITEM	PAPT NAMF	TER,NO	QTY	MATERIAL	FI

					units:	mm
△x					tolerance:	
△x					X.X	±0.2mm
△x					X.XX	±0.1mm
MARK	DESCRIPTION	DATE	REVISED	APPROVED	X.XXX	±0.05mm
REVISIONS					UNSPECIFIED TOLERANCES	

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DSND		DATE		SCALE: N/A	MODEL TYPE: TA
DWN		DATE		VIEW:	PART NO.:
CHKD		DATE		UNIT: mm	DWG NO.: TS-11
APPD		DATE		SIZE: A4	
XKB INDUSTRIAL PRECISION CO.,LIMITED					WEIGHT 1.0g